



# Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

**Adobe Reader version 7.0.5 is required to complete this declaration.**

1752-2 1.1	IPC Web Site for Information on IPC-1752 Standard <a href="http://www.ipc.org/IPC-175x">http://www.ipc.org/IPC-175x</a>	Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat
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## Supplier Information

Company Name * ST Microelectronics	Company Unique ID	Unique ID Authority	Response Date * N/A	Response Document ID				
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *					
Authorized Representative * GIANFRANCO SANTANGELO	Title - Representative APM MD CHAMPION	Phone - Representative * N/A	Email - Representative * N/A	Supplier Comments or URL for Additional Information				
Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight *	UOM	Unit Type
	STTH8L06D	HSDK*D39G01B	2010-07-08	A	SH1A	1,900	mg	Each
Alternate Recommendation	DO 220			Alternate Item Comments	ECOPACK2/ROHS;ST Internal reference BSA Doc.C			

## Manufacturing Process Information

Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	Number of Reflow Cycles
Matte Tin (Sn)	CU Alloy	Not Applicable	C	30 seconds	3

Comments  
**DISCLAIMER: While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict "as is"**

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## RoHS Material Composition Declaration

Declaration Type \*

Simplified

**RoHS Directive 2002/95/EC** **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Supplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

RoHS Declaration \*

3 - Item(s) does not contain RoHS restricted substances per the definition above except for lead in solders and selected exemptions, if any

Supplier Acceptance \*

Accepted

**Exemptions:** If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version

EL-2006/690/EC

7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).

## Declaration Signature

**Instructions:** Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

## Homogeneous Material Composition Declaration for Electronic Products

**SubItem Instructions:** The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

**Substance Instructions:** [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

**Line Functions:** +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

Item/SubItem Name	Homogeneous Material	Weight	Unit of Measure	Level	Substance Category	Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance		PPM	
											-	+		
HSDK*D39G01B	Silicon Die	5.018	mg	Supplier	Silicon die	Silicon	7440-21-3		4.93	mg			982,46	
					die metallization	Aluminium(Al)	7429-90-5		0.057	mg			11,359	
						Nickel (Ni)	7440-02-0		0.024	mg			4,783	
						Titanium (Ti)	7440-32-6		0.002	mg			399	
						Gold (Au)	7440-57-5		0.005	mg			996	
Leadframe	1,208.51	mg	supplier	alloy	Copper (Cu)	7440-50-8		1,206.945	mg			998,69		
					Iron (Fe)	7439-89-6		1.209	mg			1,000		
					Iron Phosphide (FeP)	26508-33-8		0.363	mg			300		
Leadframe coating	1.22	mg	supplier	coating	Nickel (Ni)	7440-02-0		1.187	mg			972,95		
					Phosphorus (P)	7723-14-0		0.033	mg			27,049		
Die Attach	2.865	mg	A	Lead/Lead Compound	Lead (Pb)	7439-92-1	7a. Lead	2.736	mg				954,97	
					supplier	soft solder	Silver (Ag)	7440-22-4		0.072	mg			25,131
							Tin (Sn)	7440-31-5		0.057	mg			19,895
Bonding wire	3.01	mg	Supplier	Bonding wire	Aluminium (Al)	7429-90-5		3.01	mg			1,000,0		
Encapsulation	673.311	mg	supplier	Moulding Compound	Epoxy resin	29690-82-2		134.662	mg				200,00	
					Silica, vitreous	60676-86-0		428.899	mg			637,00		
					phenolic resin	9003-35-4		67.331	mg			100,00		
					metal hydroxide	proprietary		40.399	mg			60,001		
					carbon black	1333-86-4		2.02	mg			3,000		
Finishing	6.059	mg	supplier	connection coating	Tin (Sn)	7440-31-5		6.059	mg			1,000,0		